

L Number	Hits	Search Text	DB	Time stamp
-	14	361/\$.ccls. and (chip processor) and ((vibration adj damp\$4) shock)	JPO	2004/09/27 16:16
-	659	(chip processor) and ((vibration adj damp\$4) shock)	JPO	2004/09/27 16:16
-	22591	(chip processor) and ((vibration adj damp\$4) shock)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/27 17:35
-	7	((chip processor) and ((vibration adj damp\$4) shock)) and ((chip microprocessor (integrated adj circuit)) near3 ((vibration adj damping) (shock adj absorb\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/27 16:22
-	47	((chip processor) and ((vibration adj damp\$4) shock)) and ((chip microprocessor (integrated adj circuit)) near3 ((vibration adj damping) (shock adj absorb\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/27 16:30
-	297	((chip processor) and ((vibration adj damp\$4) shock)) and (kelvin maxwell)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/27 17:36
-	136	((chip processor) and ((vibration adj damp\$4) shock)) and (maxwell)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/27 17:37
-	0	((chip processor) and ((vibration adj damp\$4) shock)) and ((maxwell kelvin) adj vibration)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/27 17:37
-	0	((chip processor) and ((vibration adj damp\$4) shock)) and ((maxwell kelvin) near2 vibration)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/27 17:37
-	0	((chip processor) and ((vibration adj damp\$4) shock)) and ((maxwell kelvin) near3 vibration)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/27 17:37
-	5	((chip processor) and ((vibration adj damp\$4) shock)) and ((maxwell kelvin) adj system)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/27 17:41
-	29	((maxwell kelvin) adj system)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/27 17:41

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